

512K (64K x 8) CMOS EPROM

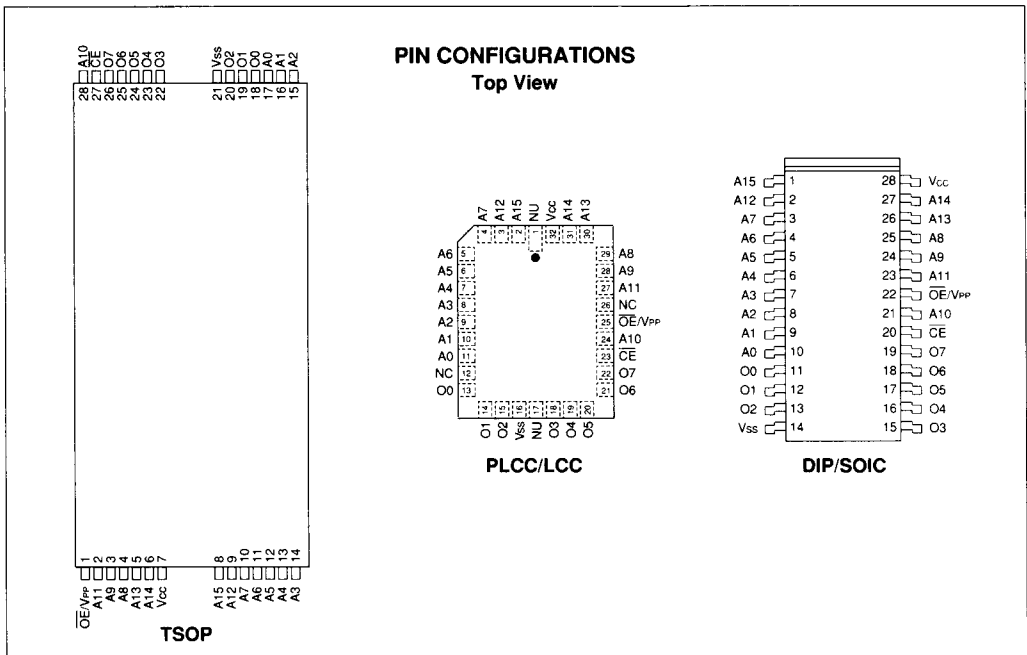
FEATURES

- High speed performance
 - 90ns access time available
- CMOS Technology for low power consumption
 - 35mA Active current
 - 100µA Standby current
- Factory programming available
- Auto-insertion-compatible plastic packages
- Auto ID™ aids automated programming
- High speed express programming algorithm
- Organized 64K x 8: JEDEC standard pinouts
 - 28-pin Dual-in-line package
 - 32-pin Chip carrier (leadless or plastic)
 - 28-pin SOIC package
 - 28-pin TSOP
 - Tape and reel
- Available for the following temperature ranges:
 - Commercial: 0° C to 70° C
 - Industrial: -40° C to 85° C
 - Automotive: -40° C to 125° C

DESCRIPTION

The Microchip Technology Inc. 27C512 is a CMOS 512Kbit (electrically) Programmable Read Only Memory. The device is organized into 64K words by 8 bits (64K bytes). Accessing individual bytes from an address transition or from power-up (chip enable pin going low) is accomplished in less than 90ns. This very high speed device allows the most sophisticated microprocessors to run at full speed without the need for WAIT states. CMOS design and processing enables this part to be used in systems where reduced power consumption and high reliability are requirements.

A complete family of packages is offered to provide the most flexibility in applications. For surface mount applications, PLCC or SOIC packaging is available. Tape or reel packaging is also available for PLCC or SOIC packages. UV erasable versions are also available.



PIN FUNCTION TABLE	
Name	Function
A0 - A15	Address Inputs
\overline{CE}	Chip Enable
\overline{OE}/VPP	Output Enable/ Programming Voltage
O0 - O7	Data Output
VCC	+5V Power Supply
VSS	Ground
NC	No Connection; No Internal Connection
NU	Not Used; No External Connection Is Allowed

ELECTRICAL CHARACTERISTICS

Maximum Ratings*

VCC and input voltages w.r.t. VSS -0.6V to +7.25V
 VPP voltage w.r.t. VSS during
 programming -0.6V to +14.0V
 Voltage on A9 w.r.t. VSS -0.6V to +13.5V
 Output voltage w.r.t. VSS -0.6V to VCC + 1.0V
 Storage temperature -65° C to 150° C
 Ambient temp. with power applied -65° C to 125° C

*Notice: Stresses above those listed under "Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

READ OPERATION		VCC = +5V ±10%					
DC Characteristics		Commercial:		Tamb = 0° C to 70° C			
		Industrial:		Tamb = -40° C to 85° C			
		Extended (Automotive):		Tamb = -40° C to 125° C			
Parameter	Part*	Status	Symbol	Min	Max	Units	Conditions
Input Voltages	all	Logic "1"	V _{IH}	2.0	V _{CC} +1	V	
		Logic "0"	V _{IL}	-0.5	0.8	V	
Input Leakage	all		I _{LI}	-10	10	µA	V _{IN} = 0 to V _{CC}
Output Voltages	all	Logic "1"	V _{OH}	2.4		V	I _{OH} = -400µA I _{OL} = 2.1mA
		Logic "0"	V _{OL}		0.45	V	
Output Leakage	all		I _{LO}	-10	10	µA	V _{OUT} = 0V to V _{CC}
Input Capacitance	all		C _{IN}		6	pF	V _{IN} = 0V; Tamb = 25° C; f = 1MHz
Output Capacitance	all		C _{OUT}		12	pF	V _{OUT} = 0V; Tamb = 25° C; f = 1MHz
Power Supply Current, Active	C	TTL input	I _{CC}		35	mA	V _{CC} = 5.5V f = 1MHz; $\overline{OE}/VPP = \overline{CE} = V_{IL}$; I _{out} = 0mA; V _{IL} = -0.1 to 0.8 V; V _{IH} = 2.0 to V _{CC} ; Note (1)
	I, E	TTL input	I _{CC}		45	mA	
Power Supply Current, Standby	C	TTL input	I _{CC(S)TTL}		2	mA	$\overline{CE} = V_{CC} \pm 0.2V$
	I, E	TTL input	I _{CC(S)TTL}		3	mA	
	C	CMOS input	I _{CC(S)CMOS}		100	µA	

* Parts: C = Commercial Temperature Range; I, E = Industrial and Extended Temperature Ranges
 Notes: (1) Active current increases 2 mA per MHz up to operating frequency for all temperature ranges.

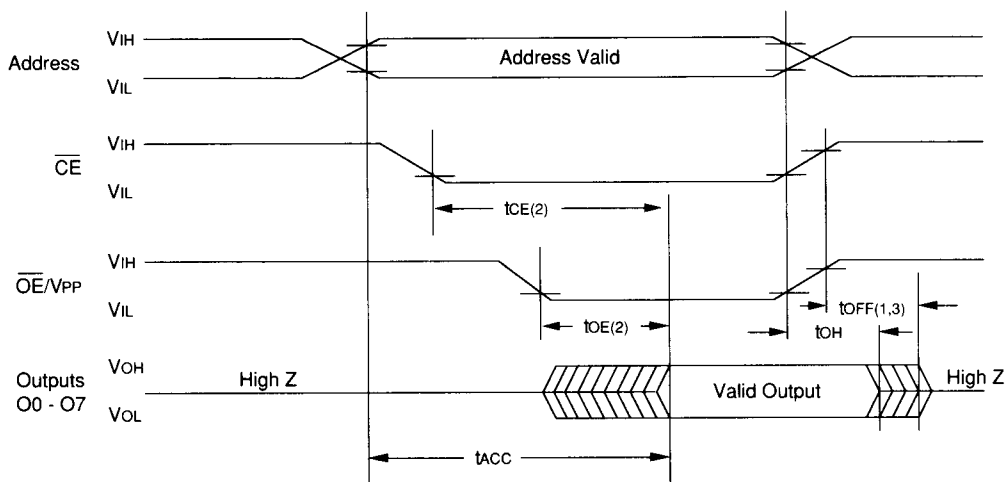
READ OPERATION AC Characteristics

AC Testing Waveform: $V_{IH} = 2.4V$ and $V_{IL} = .45V$; $V_{OH} = 2.0V$ and $V_{OL} = 0.8V$
 Output Load: 1 TTL Load + 100pF
 Input Rise and Fall Times: 10nsec
 Ambient Temperature: Commercial: $T_{amb} = 0^\circ C$ to $70^\circ C$
 Industrial: $T_{amb} = -40^\circ C$ to $85^\circ C$
 Extended (Automotive): $T_{amb} = -40^\circ C$ to $125^\circ C$

Parameter	Sym	27C512-90		27C512-10		27C512-12		27C512-15		27C512-20		Units	Conditions
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max		
Address to Output Delay	t_{ACC}		90		100		120		150		200	ns	$\overline{CE} = \overline{OE}/V_{PP} = V_{IL}$
\overline{CE} to Output Delay	t_{CE}		90		100		120		150		200	ns	$\overline{OE}/V_{PP} = V_{IL}$
\overline{OE} to Output Delay	t_{OE}		40		40		50		60		75	ns	$\overline{CE} = V_{IL}$
\overline{OE} to Output High Impedance	t_{OFF}	0	35	0	35	0	40	0	45	0	55	ns	
Output Hold from Address, \overline{CE} or \overline{OE}/V_{PP} , whichever occurred first	t_{OH}	0		0		0		0		0		ns	

* -90 AC Testing Waveform: $V_{IH} = 2.4V$ and $V_{IL} = .45V$; $V_{OH} = 1.5V$ and $V_{OL} = 1.5V$
 Output Load: 1 TTL Load + 30pF

READ WAVEFORMS

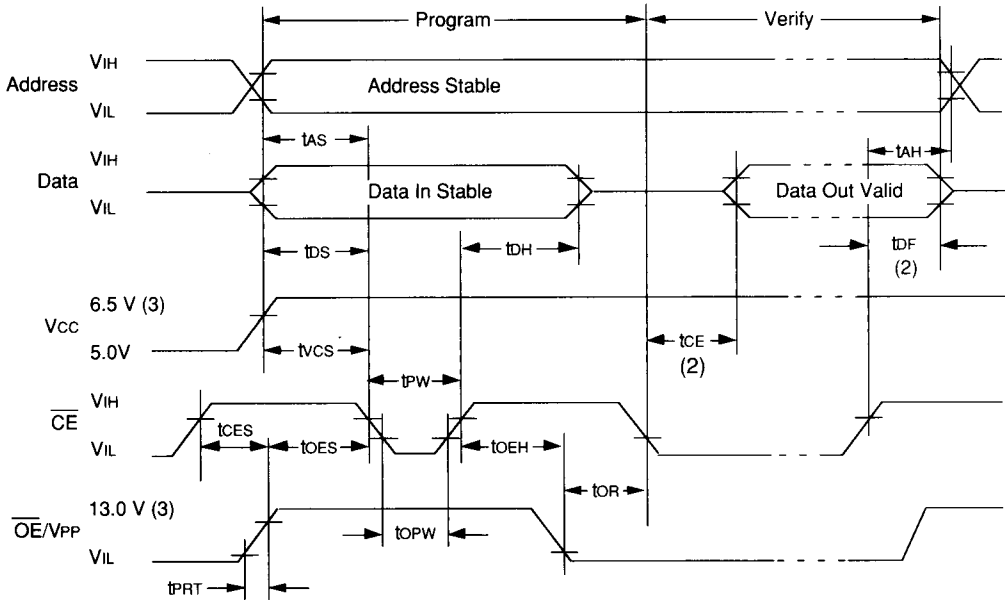


- Notes: (1) t_{OFF} is specified for \overline{OE}/V_{PP} or \overline{CE} , whichever occurs first
 (2) \overline{OE} may be delayed up to $t_{CE} - t_{OE}$ after the falling edge of \overline{CE} without impact on t_{CE}
 (3) This parameter is sampled and is not 100% tested.

PROGRAMMING DC Characteristics		Ambient Temperature: 25° C ±5° C VCC = 6.5V ± 0.25V, OE/VPP = VH = 13.0V ± 0.25V				
Parameter	Status	Symbol	Min	Max	Units	Conditions (See Note 1)
Input Voltages	Logic "1"	V _{IH}	2.0	V _{CC} +1	V	
	Logic "0"	V _{IL}	-0.1	0.8	V	
Input Leakage		I _{LI}	-10	10	μA	V _{IN} = 0V to V _{CC}
Output Voltages	Logic "1"	V _{OH}	2.4		V	I _{OH} = -400μA
	Logic "0"	V _{OL}		0.45	V	I _{OL} = 2.1mA
V _{CC} Current, program & verify		I _{CC2}		35	mA	
OE/VPP Current, program		I _{PP2}		25	mA	$\overline{CE} = V_{IL}$
A9 Product Identification		V _{ID}	11.5	12.5	V	
Note: (1) V _{CC} must be applied simultaneously or before the V _{PP} voltage on OE/VPP and removed simultaneously or after the V _{PP} voltage on OE/VPP.						

PROGRAMMING AC Characteristics		AC Testing Waveform: V _{IH} = 2.4V and V _{IL} = 0.45V; V _{OH} = 2.0V; V _{OL} = 0.8V Ambient Temperature: 25° C ±5° C VCC = 6.5V ± 0.25V, OE/VPP = VH = 13.0V ± 0.25V				
Parameter	Symbol	Min	Max	Units	Remarks	
Address Set-Up Time	t _{AS}	2		μs		
Data Set-Up Time	t _{DS}	2		μs		
Data Hold Time	t _{DH}	2		μs		
Address Hold Time	t _{AH}	0		μs		
Float Delay (2)	t _{DF}	0	130	ns		
V _{CC} Set-Up Time	t _{VCS}	2		μs		
Program Pulse Width (1)	t _{PW}	95	105	μs	100μs typical	
\overline{CE} Set-Up Time	t _{CES}	2		μs		
\overline{OE} Set-Up Time	t _{OES}	2		μs		
\overline{OE} Hold Time	t _{OEH}	2		μs		
\overline{OE} Recovery Time	t _{OR}	2		μs		
$\overline{OE/VPP}$ Rise Time During Programming	t _{PRT}	50		ns		
Notes: (1) For express algorithm, initial programming width tolerance is 100μsec ± 5%. (2) This parameter is only sampled and not 100% tested. Output float is defined as the point where data is no longer driven (see timing diagram).						

PROGRAMMING
Waveforms (1)



- Notes: (1) The input timing reference level is 0.8 V for VIL and 2.0 V for VIH.
 (2) tDF and tOE are characteristics of the device but must be accommodated by the programmer.
 (3) VCC = 6.5 V ± 0.25 V, VPP = VH = 13.0 V ± 0.5 V for express programming algorithm.

MODES

Operation Mode	\overline{CE}	$\overline{OE/VPP}$	A9	O0 - O7
Read	VIL	VIL	X	DOUT
Program	VIL	VH	X	DIN
Program Verify	VIL	VIL	X	DOUT
Program Inhibit	VIH	VH	X	High Z
Standby	VIH	X	X	High Z
Output Disable	VIL	VIH	X	High Z
Identity	VIL	VIL	VH	Identity Code

X = Don't Care

Read Mode

(See Timing Diagrams and AC Characteristics)

Read Mode is accessed when

- a) the \overline{CE} pin is low to power up (enable) the chip
- b) the $\overline{OE/VPP}$ pin is low to gate the data to the output pins.

For Read operations, if the addresses are stable, the address access time (tACC) is equal to the delay from CE to output (tCE). Data is transferred to the output after a delay (tOE) from the falling edge of $\overline{OE/VPP}$.

Standby Mode

The standby mode is defined when the \overline{CE} pin is high and a program mode is not identified.

When this condition is met, the supply current will drop from 35mA to 100 μ A.

Output Enable \overline{OE}/V_{PP}

This multifunction pin eliminates bus connection in multiple bus microprocessor systems and the outputs go to high impedance when:

- the \overline{OE}/V_{PP} pin is high (V_{IH}).

When a V_H input is applied to this pin, it supplies the programming voltage (V_{PP}) to the device.

Erase Mode (UV Windowed Versions)

Windowed products offer the ability to erase the memory array. The memory matrix is erased to the all "1's" state as a result of being exposed to ultraviolet light. To ensure complete erasure, a dose of 15 watt-second/cm² is required. This means that the device window must be placed within one inch and directly underneath an ultraviolet lamp with a wavelength of 2537 Angstroms, intensity of 12,000 μ W/cm² for approximately 20 minutes.

Programming Mode

The Express algorithm has been developed to improve on the programming throughput times in a production environment. Up to 10 100-microsecond pulses are applied until the byte is verified. A flowchart of the Express algorithm is shown in Figure 1.

Programming takes place when:

- a) V_{CC} is brought to the proper voltage,
- b) \overline{OE}/V_{PP} is brought to the proper V_H level, and
- c) CE line is low.

Since the erased state is "1" in the array, programming of "0" is required. The address to be programmed is set via pins A0 - A15 and the data to be programmed is presented to pins O0 - O7. When data and address are stable, a low going pulse on the \overline{CE} line programs that location.

Verify

After the array has been programmed it must be verified to ensure all the bits have been correctly programmed. This mode is entered when all the following conditions are met:

- a) V_{CC} is at the proper level,
- b) the \overline{OE}/V_{PP} pin is low, and
- c) the CE line is low.

Inhibit

When programming multiple devices in parallel with different data, only \overline{CE} needs to be under separate control to each device. By pulsing the \overline{CE} line low on a particular device, that device will be programmed; all other devices with CE held high will not be programmed with the data (although address and data will be available on their input pins).

Identity Mode

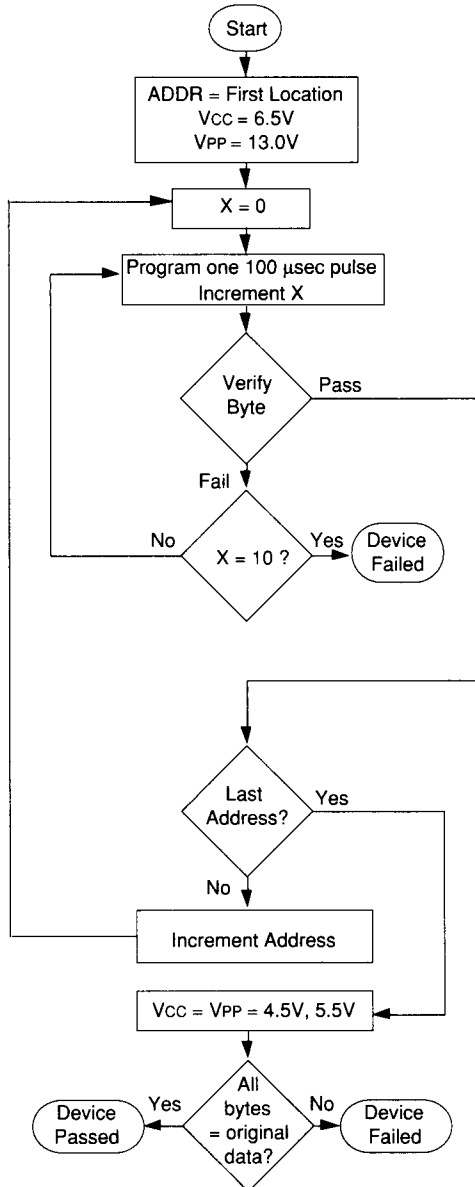
In this mode specific data is output which identifies the manufacturer as Microchip Technology Inc and the device type. This mode is entered when Pin A9 is taken to V_H (11.5V to 12.5V). The \overline{CE} and \overline{OE}/V_{PP} lines must be at V_{IL} . A0 is used to access any of the two non-erasable bytes whose data appears on O0 through O7.

Pin \rightarrow	Input	Output								
Identity \downarrow	A0	O7	O6	O5	O4	O3	O2	O1	O0	Hex
	Manufacturer Device Type*	V_{IL}	0	0	1	0	1	0	0	1
	V_{IH}	0	0	0	0	1	1	0	1	0D

* Code subject to change.

PROGRAMMING - FIGURE 1 EXPRESS ALGORITHM

Conditions:
 $T_{amb} = 25^{\circ}C \pm 5^{\circ}C$
 $V_{CC} = 6.5 \pm 0.25V$
 $V_{PP} = 13.0 \pm 0.25V$



27C512

SALES AND SUPPORT

To order or to obtain information, e.g., on pricing or delivery, please use the listed part numbers, and refer to the factory or the listed sales offices.

PART NUMBERS

27C512 - 25 I / P

Package:	J	Cerdip
	K	Ceramic Leadless Chip Carrier
	L	Plastic Leaded Chip Carrier
	P	Plastic DIP
	SO	Plastic SOIC
	TS	TSOP
Temperature Range:	-	0° C to 70° C
	I	-40° C to 85° C
	E	-40° C to 125° C
Access Time:	90	90 nsec
	10	100 nsec
	12	120 nsec
	15	150 nsec
	20	200 nsec
Device:	27C512	512K (64K x 8) CMOS EPROM